

Product Technical Data Sheet

AG Copper

Copper-based heat conducting paste filling the processor-radiator connections to improve cooling. Thermal conductivity ~ 3.1 W/mK.

Application:

filling the processor-radiator connections,
not suitable for aluminium radiators,
does not conduct electricity.

Physicochemical properties:

Parameters	UoM	Result
Appearance	-	paste, copper-based
Odour	-	odourless
Melting point	°C	-50
Flash point	°C	350
Density	g/cm ³	2,9
Operating temperature range	°C	-50 ~ 250

Packagings:

Volume	Type of packaging	Collective packaging	Item Code
1,5 ml	syringe	5	ART.AGT-060
14 ml	syringe	2	ART.AGT-061

Warehousing:

Store in a well-ventilated, cool and dry place. Keep containers tightly closed when not in use. Protect against sunlight exposure.

Data contained in this document are consistent with the current state of our knowledge. They describe typical product properties and applications. However, it is up to the user to examine the suitability of this product for specific applications. We deny liability for the obtained results on the grounds that application conditions lie beyond our control.